

LC322271J, M, T-70/80

2 MEG (131072 words × 16 bits) DRAM Fast Page Mode, Byte Write

Preliminary

Overview

The LC322271J, M and T is a CMOS dynamic RAM operating on a single 5 V power source and having a 131072 words × 16 bits configuration. Equipped with large capacity capabilities, high speed transfer rates and low power dissipation, this series is suited for a wide variety of applications ranging from computer main memory and expansion memory to commercial equipment.

Address input utilizes a multiplexed address bus which permits it to be enclosed in a compact plastic package of SOJ 40-pin, SOP 40-pin, and TSOP 44-pin . Refresh rates are within 8 ms with 512 row address (A0 to A7, A8R) selection and support Row Address Strobe (\overline{RAS})-only refresh, Column Address Strobe (\overline{CAS})-before- \overline{RAS} refresh and hidden refresh settings. There are functions such as fast page mode, read-modify-write and byte write. The pin assignment follows the JEDEC 1 M DRAM (65536 words × 16 bits, $1\overline{CAS}/2\overline{WE}$) standard.

Features

- 131072 words × 16 bits configuration.
- Single 5 V \pm 10% power supply.
- All input and output (I/O) TTL compatible.
- Supports fast page mode, read-modify-write and byte write
- Supports output buffer control using early write and Output Enable (OE) control.
- 8 ms refresh using 512 refresh cycles.
- Supports RAS-only refresh, CAS-before-RAS refresh and hidden refresh.
- Follows the JEDEC 1 M DRAM (65536 words \times 16 bits, $1\overline{\text{CAS}}/2\overline{\text{WE}}$) standard.
- RAS access time/column address time/CAS access time/cycle time/power dissipation

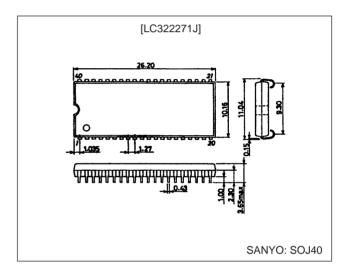
• Package:

SOJ 40-pin (400 mil) plastic package: LC322271J SOP 40-pin (450 mil) plastic package: LC322271M TSOP 44-pin (400 mil) plastic package: LC322271T

Package Dimensions

unit: mm

3200-SOJ40



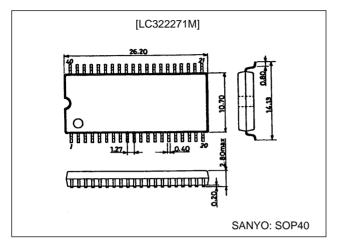
Parameter		LC32227	LC322271J, M, T			
		-70	-80			
RAS access time		70 ns	80 ns			
Column address access time		35 ns	45 ns			
CAS access time		20 ns	30 ns			
Cycle time		130 ns	150 ns			
Power dissipation (max.)	During operation	688 mW	633 mW			
	During standby	5.5 mW (CMOS lev	el)/11 mW (TTL level)			

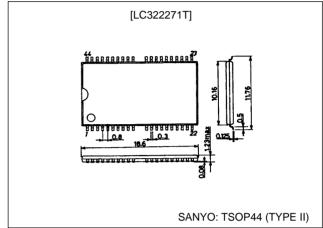
Package Dimensions

unit: mm

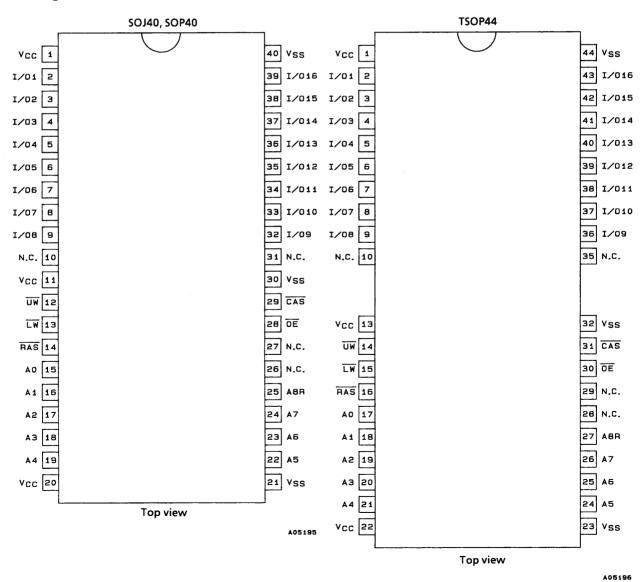
3195-SOP40



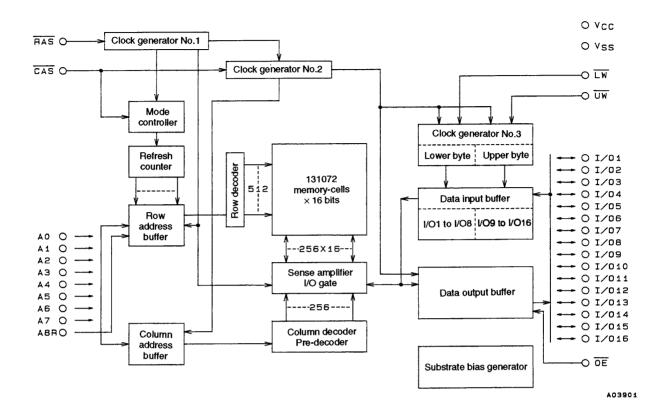




Pin Assignments



Block Diagram



Specifications

Absolute Maximum Ratings

Param	neter	Symbol	Ratings	Unit	Note
Maximum supply voltage		V _{CC} max	-1.0 to +7.0	V	1
Input voltage		V _{IN}	-1.0 to +7.0	V	1
Output voltage		V _{OUT}	-1.0 to +7.0	V	1
Allowable power dissipation	LC322271J, M	Pd max	800	mW	1
	LC322271T	Tulliax	700] ''''V	'
Output short-circuit current		I _{OUT}	50	mA	1
Operating temperature range		Topr	0 to +70	°C	1
Storage temperature range		Tstg	−55 to +150	°C	1

Note: 1. Stresses greater than the above listed maximum values may result in damage to the device.

DC Recommended Operating Ranges at Ta = 0 to +70°C

Parameter	Symbol	min	typ	max	Unit	Note
Power supply voltage	V _{CC}	4.5	5.0	5.5	V	2
Input high level voltage	V _{IH}	2.4		6.5	V	2
Input low level voltage (A0 to A7, A8R, RAS, CAS, UW, LW, OE)	V _{IL}	-1.0*		+0.8	V	2
Input low level voltage (I/O1 to I/O16)	V _{IL}	-0.5*		+0.8	V	2

DC Electrical Characteristics at Ta = 0 to +70°C, V_{CC} = 5 V \pm 10%

			LC322271J, M, T					
Parameter	Symbol	Conditions		70	-80		Unit	Note
			min	max	min	max		
Operating current (Average current during operation)	I _{CC1}	\overline{RAS} , \overline{CAS} , address cycling: $t_{RC} = t_{RC}$ min		125		115	mA	3, 4, 5
Standby current	I _{CC2}	$\overline{RAS} = \overline{CAS} = V_{IH}$		2		2	mA	
RAS-only refresh current	I _{CC3}	\overline{RAS} cycling, $\overline{CAS} = V_{IH}$: $t_{RC} = t_{RC}$ min		125		115	mA	3, 5
Fast page mode current	I _{CC4}	$\overline{RAS} = V_{IL}$, \overline{CAS} , address cycling: $t_{PC} = t_{PC}$ min		115		90	mA	3, 4, 5
Standby current	I _{CC5}	$\overline{RAS} = \overline{CAS} = V_{CC} - 0.2 \text{ V}$		1		1	mA	
CAS-before-RAS refresh current	I _{CC6}	\overline{RAS} , \overline{CAS} cycling: $t_{RC} = t_{RC}$ min		125		115	mA	3
Input leakage current	I _{IL}	$0 \text{ V} \le V_{IN} \le 6.5 \text{ V}$, pins other than test pin = 0 V	-10	+10	-10	+10	μA	
Output leakage current	I _{OL}	D _{OUT} disable, 0 V ≤ V _{OUT} ≤ 5.5 V	-10	+10	-10	+10	μA	
Output high level voltage	V _{OH}	I _{OUT} = -2.5 mA	2.4		2.4		V	
Output low level voltage	V _{OL}	I _{OUT} = 2.1 mA		0.4		0.4	V	

- Note: 3. All current values are measured at minimum cycle rate. Since current flows immoderately, if cycle time is longer than shown here, current value

 - 4. I_{CC1} and I_{CC4} are dependent on output loads. Maximum values for I_{CC1} and I_{CC4} represent values with output open.
 5. Address change is less than or equal to one time during RAS = V_{IL}. Concerning I_{CC4}, it is less than or equal to one time during 1 cycle (t_{PC}).

AC Electrical Characteristics at Ta = 0 to +70 $^{\circ}C,\,V_{CC}$ = 5 V \pm 10% (Notes 6, 7 and 8)

Parameter	Symbol	-70			80	Unit	Note
Falanetei	Symbol	min	max	min	max	Unit	Note
Random read, write cycle time	t _{RC}	130		150		ns	
Read-write/read-modify-write cycle time	t _{RWC}	190		200		ns	
Fast page mode cycle time	t _{PC}	45		55		ns	
Fast page mode read-write/read-modify-write cycle time	t _{PRWC}	95		100		ns	
RAS access time	t _{RAC}		70		80	ns	9, 14, 15
CAS access time	t _{CAC}		20		30	ns	9, 14
Column address access time	t _{AA}		35		45	ns	9, 15
CAS precharge access time	t _{CPA}		40		50	ns	9
Output low-impedance time from CAS low	t _{CLZ}	0		0		ns	9
Output buffer turn-off delay time	t _{OFF}	0	20	0	20	ns	10
Rise, fall time	t _T	3	50	3	50	ns	
RAS precharge time	t _{RP}	50		60		ns	
RAS pulse width	t _{RAS}	70	10000	80	10000	ns	
RAS pulse width for fast page mode cycle only	t _{RASP}	70	100000	80	100000	ns	

Note: 2. All voltages are referenced to V_{SS}.
*: -2.0 V when pulse width is less than 20 ns.

LC322271J, M, T-70/80

Continued from preceding page.

		-70		-80			Niete
Parameter	Symbol	min	max	min	max	Unit	Note
RAS hold time	t _{RSH}	20		30		ns	
CAS hold time	t _{CSH}	70		80		ns	
CAS pulse width	t _{CAS}	20	10000	30	10000	ns	
RAS to CAS delay time	t _{RCD}	25	50	25	50	ns	14
RAS to column address delay time	t _{RAD}	17	35	17	35	ns	15
CAS to RAS precharge time	t _{CRP}	10		10		ns	
CAS precharge time	t _{CP}	10		10		ns	
Row address setup time	t _{ASR}	0		0		ns	
Row address hold time	t _{RAH}	12		12		ns	
Column address setup time	t _{ASC}	0		0		ns	
Column address hold time	t _{CAH}	15		20		ns	
Column address hold time referenced to RAS	t _{AR}	50		60		ns	
Column address to RAS lead time	t _{RAL}	40		45		ns	
Read command setup time	t _{RCS}	0		0		ns	
Read command hold time referenced to $\overline{\text{CAS}}$	t _{RCH}	0		0		ns	11
Read command hold time referenced to RAS	t _{RRH}	0		0		ns	11
Write command hold time	twch	15		15		ns	
Write command hold time referenced to RAS	t _{WCR}	50		60		ns	
Write command pulse width	t _{WP}	15		15		ns	
Write command to RAS lead time	t _{RWL}	25		25		ns	
Write command to CAS lead time	t _{CWL}	20		20		ns	
Data input setup time	t _{DS}	0		0		ns	12
Data input hold time	t _{DH}	15		20		ns	12
Data input hold time referenced to RAS	t _{DHR}	50		60		ns	
Refresh time	t _{REF}		8		8	ms	
Write command setup time	t _{WCS}	0		0		ns	13
CAS to UW, LW delay time	t _{CWD}	50		50		ns	13
RAS to UW, LW delay time	t _{RWD}	100		100		ns	13
Column address to UW, LW delay time	t _{AWD}	65		65		ns	13
CAS precharge UW, LW delay time for fast page mode cycle only	t _{CPWD}	70		70		ns	13
CAS setup time for CAS-before-RAS	t _{CSR}	10		10		ns	
CAS hold time for CAS-before-RAS	t _{CHR}	15		15		ns	
RAS precharge CAS active time	t _{RPC}	10		10		ns	
CAS precharge time for CAS-before-RAS counter test	tCPT	40		40		ns	
RAS hold time referenced to $\overline{\text{OE}}$	t _{ROH}	15		15		ns	
OE access time	t _{OEA}		20		25	ns	9
OE delay time	t _{OED}	15		15		ns	
OE output buffer turn-off delay time		0		0	15	ns	10
OE command hold time	^T OEZ				1		
Data input to CAS delay time	t _{OEZ}	20		20		ns	
	t _{OEH}	20		20		ns ns	16
Data input to OE delay time	t _{OEH}						16 16
Data input to $\overline{\text{OE}}$ delay time Masked write setup time	t _{OEH} t _{DZC} t _{DZO}	0		0		ns	-
	t _{OEH}	0		0		ns ns	-

LC322271J, M, T-70/80

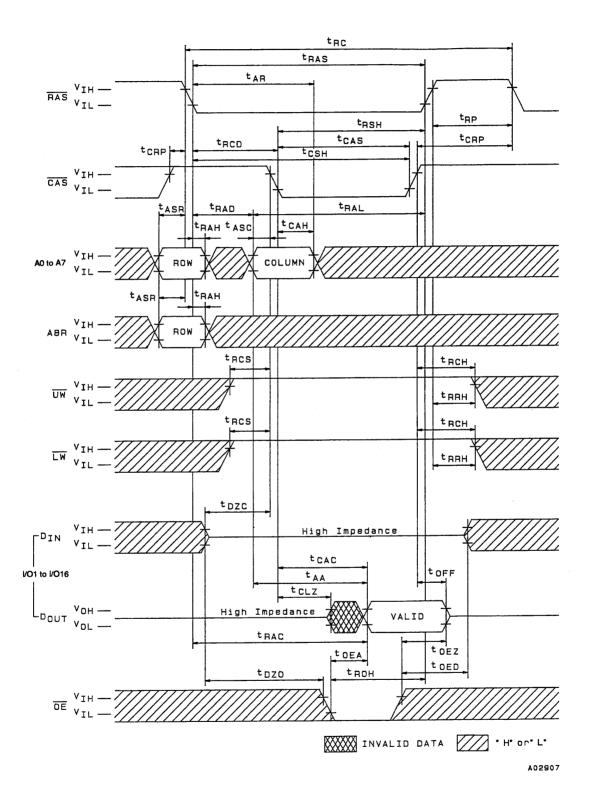
Input/Output Capacitance at Ta = 25° C, f = 1 MHz, V_{CC} = $5~V \pm 10\%$

Parameter	Symbol	min	max	Unit	Note
Input capacitance (A0 to A7, A8R, RAS, CAS, UW, LW, OE)	C _{IN}		7	pF	
Input/Output capacitance (I/O1 to I/O16)	C _{I/O}		7	pF	

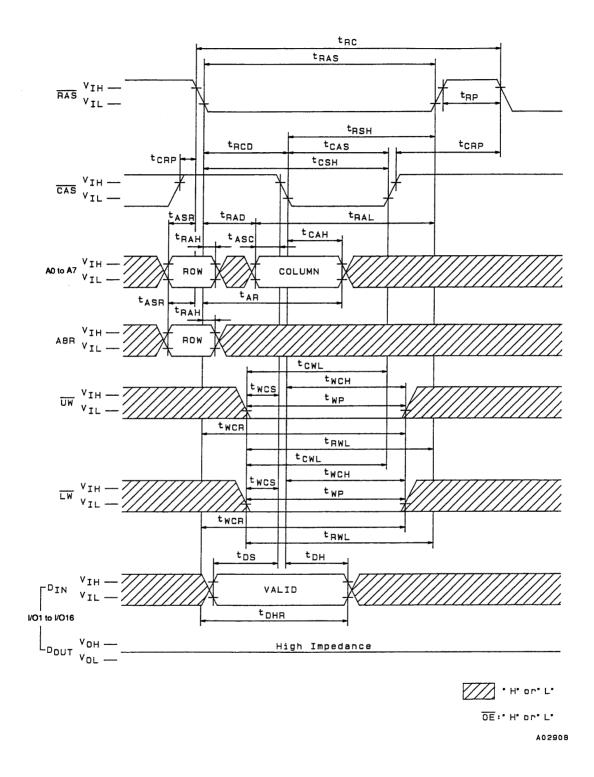
- Note: 6. An initial pause of 200 µs is required after power-up followed by eight RAS-only refresh cycles before proper device operation is achieved. In case of using refresh counter, a minimum of eight CAS-before-RAS refresh cycles instead of eight RAS-only refresh cycles are required.
 - 7. Measured at $t_T = 5$ ns.
 - 8. When measuring input signal timing, V_{IH} (min) and V_{IL} (max) are used for reference points. In addition, rise and fall time are defined between V_{IH} and V_{II}.
 - 9. Measured using an equivalent of 50 pF and one standard TTL loads.
 - 10. t_{OFF} (max) and t_{OEZ} (max) are defined as the time until output voltage can no longer be measured when output switches to a high impedance condition.
 - 11. Operation is guaranteed if either t_{RRH} or t_{RCH} is satisfied.
 - 12. These parameters are measured from the falling edge of CAS for an early-write cycle, and from the falling edge of UW and LW for a read-write/read-modify-write cycle.
 - 13. t_{WCS}, t_{CWD}, t_{RWD}, t_{AWD} and t_{CPWD} are not restrictive operating parameters for memory in that they specify the operating mode. If t_{WCS} ≥ t_{WCS} (min), the cycle switches to an early-write cycle and output pins switch to high impedance throughout the cycle.
 - If $t_{CWD} \ge t_{CWD}$ (min), $t_{RWD} \ge t_{RWD}$ (min), $t_{AWD} \ge t_{AWD}$ (min) and $t_{CPWD} \ge t_{CPWD}$ (min) for fast page mode cycle only, the cycle switches to a read-write/read-modify-write cycle and data output equal information in the selected cells. If neither of the above timings are satisfied, output pins are in an undefined state.
 - 14. t_{RCD} (max) is not a restrictive operating parameter but instead represents the point at which the access time t_{RAC} (max) is guaranteed. If t_{RCD} ≥ t_{RCD} (max), access time is determined according to t_{CAC}.
 15. t_{RAD} (max) is not a restrictive operating parameter but instead represents the point at which the access time t_{RAC} (max) is guaranteed. If t_{RAD} ≥
 - 15. t_{RAD} (max) is not a restrictive operating parameter but instead represents the point at which the access time t_{RAC} (max) is guaranteed. If t_{RAD} ≥ t_{RAD} (max), access time is determined according to t_{AA}.
 - 16. Operation is guaranteed if either t_{DZC} or t_{DZO} i s satisfied.

Timing Chart

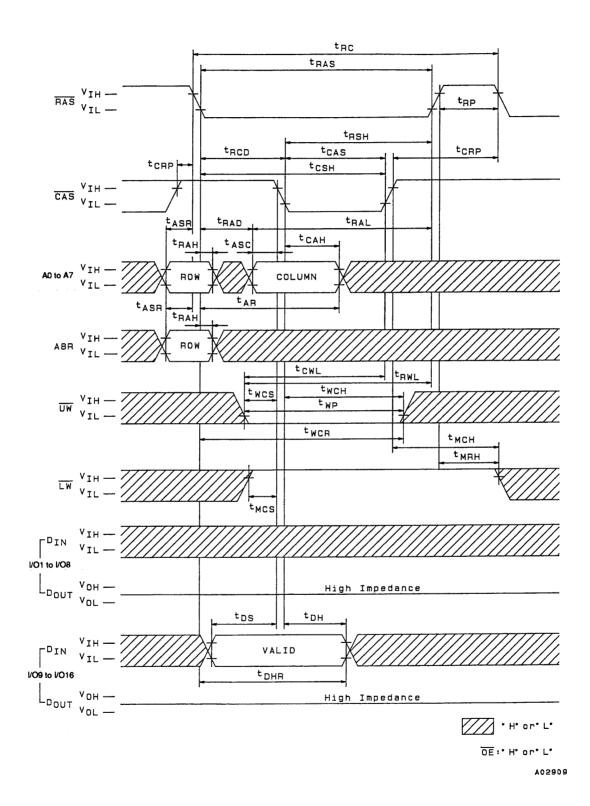
Read Cycle



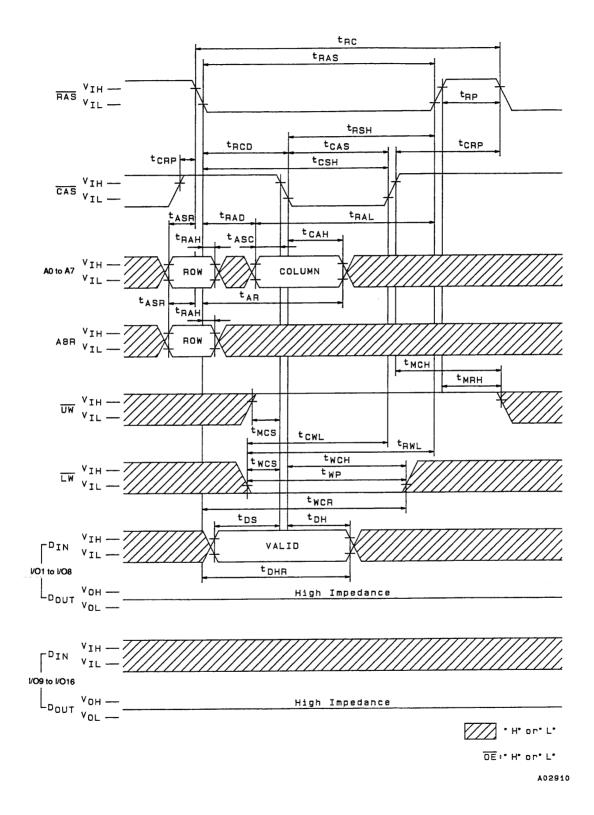
Early Write Cycle



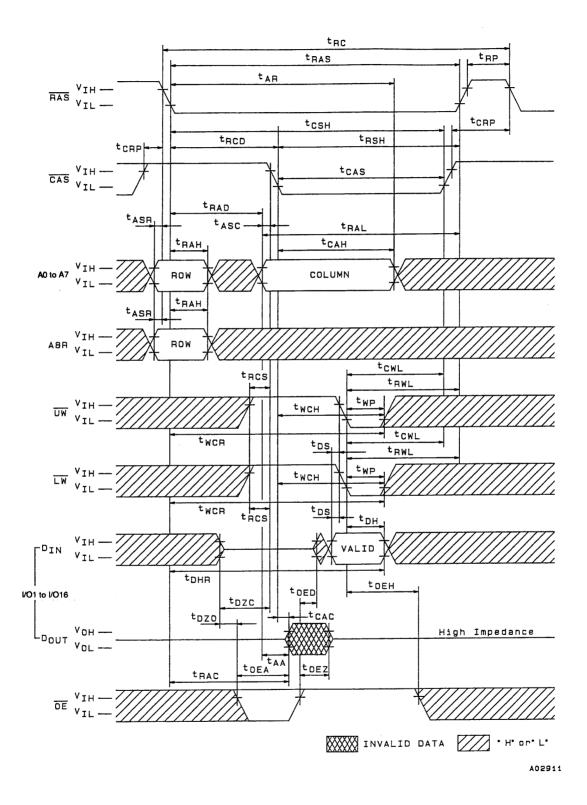
Upper Byte Early Write Cycle



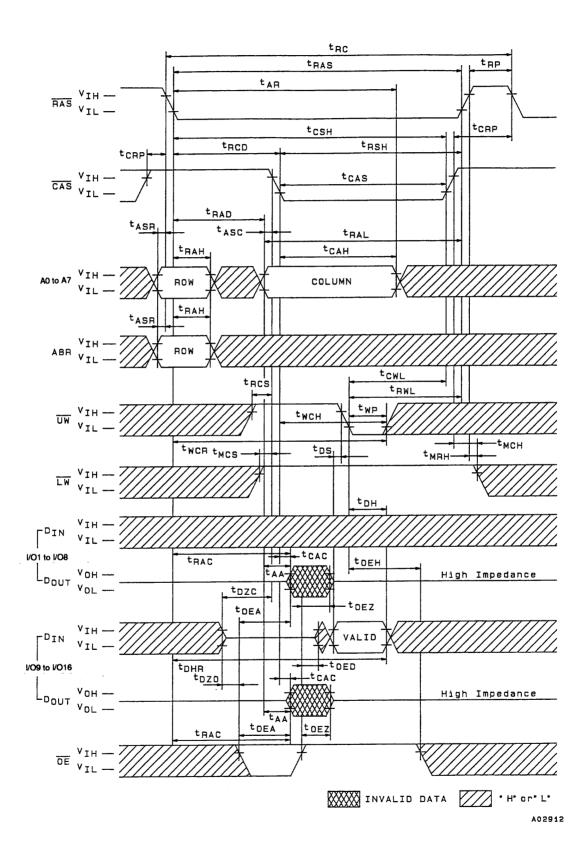
Lower Byte Early Write Cycle



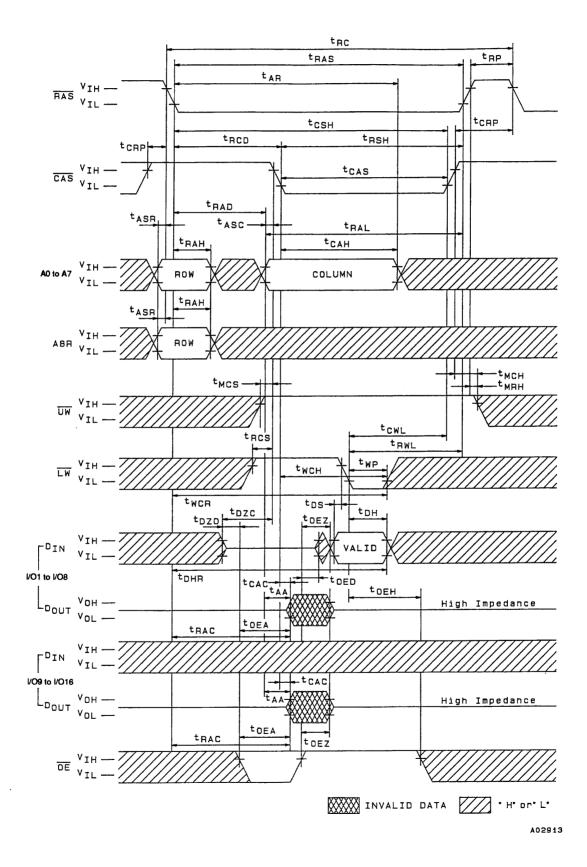
Write Cycle (OE Control)



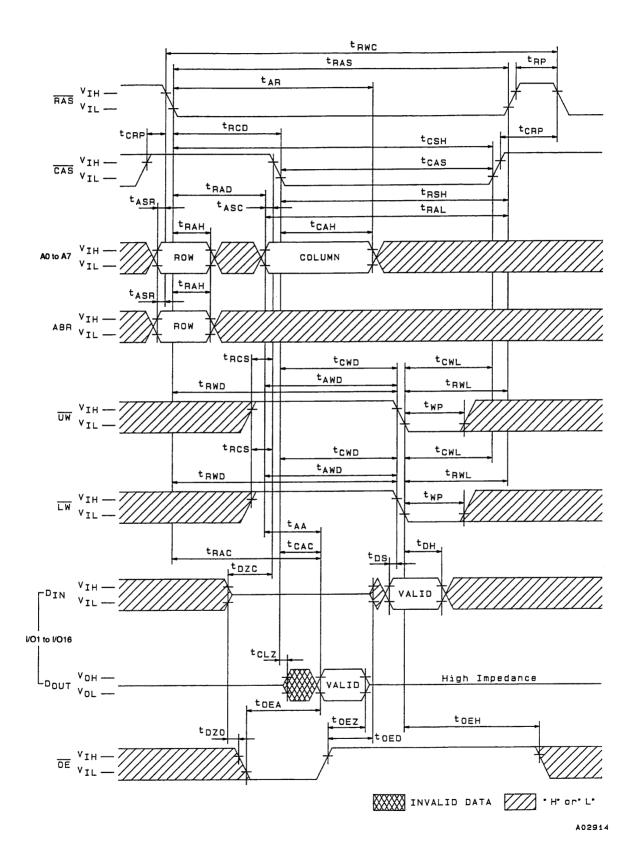
Upper Byte Write Cycle (OE Control)



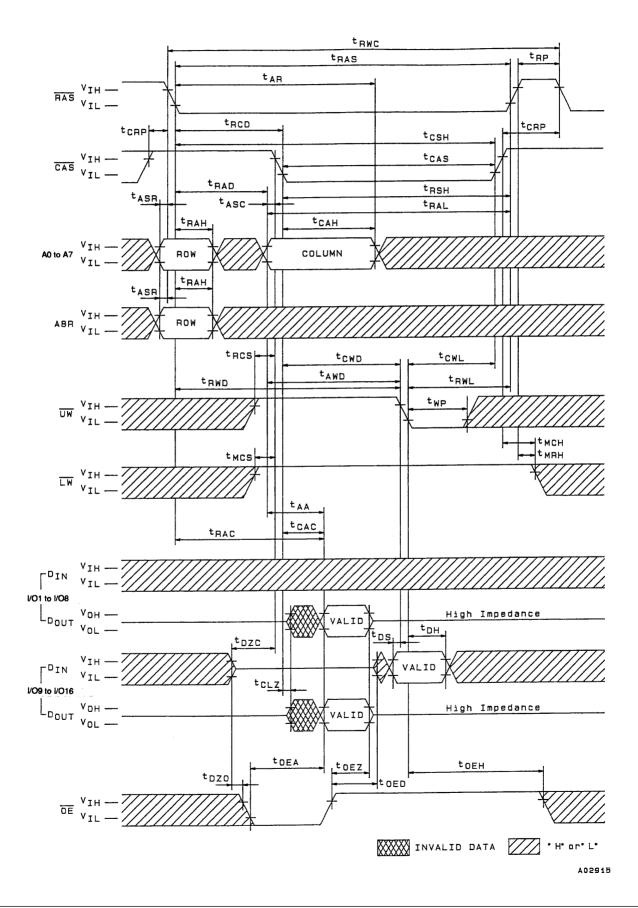
Lower Byte Write Cycle (OE Control)



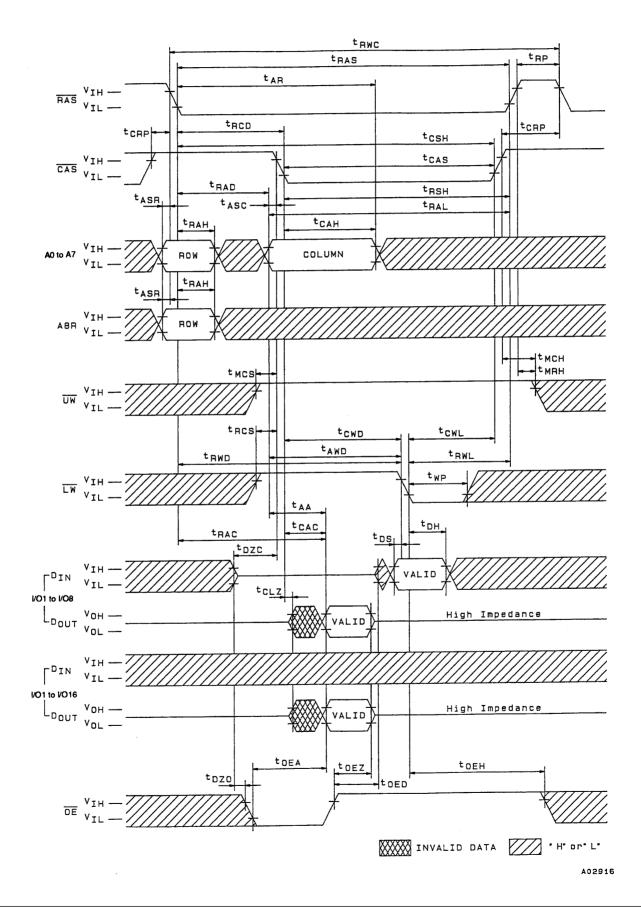
Read-Modify-Write Cycle



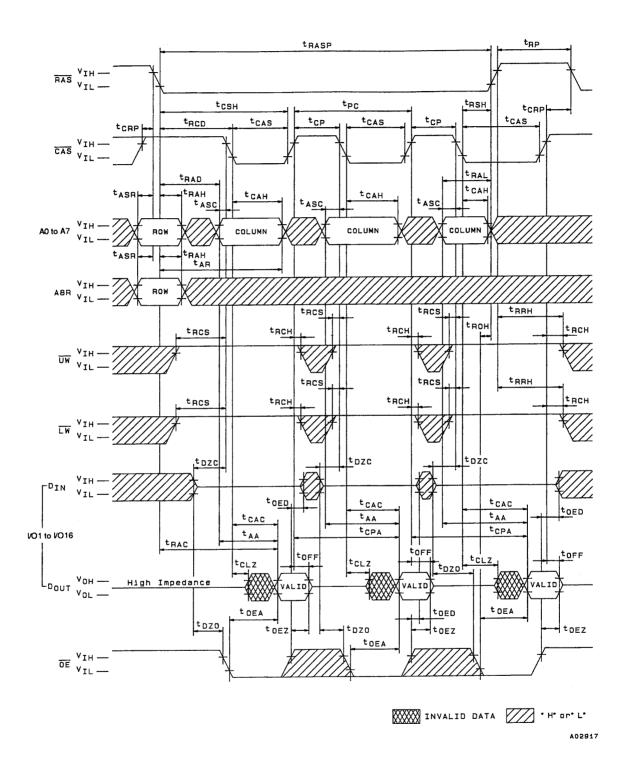
Read-Modify Upper Byte Write Cycle



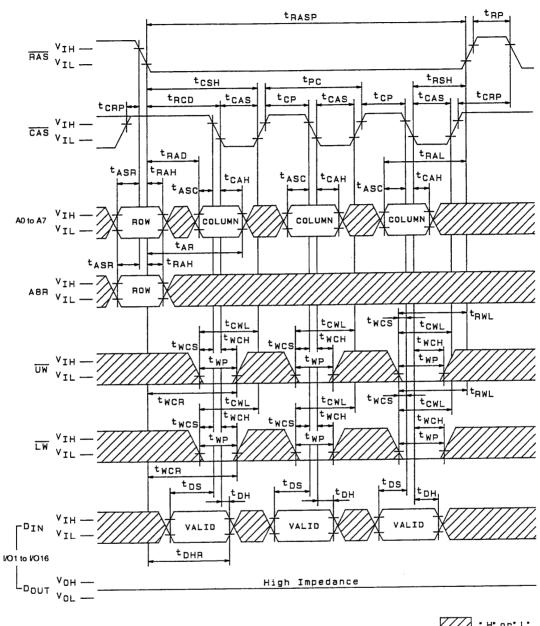
Read-Modify Lower Byte Write Cycle



Fast Page Mode Read Cycle

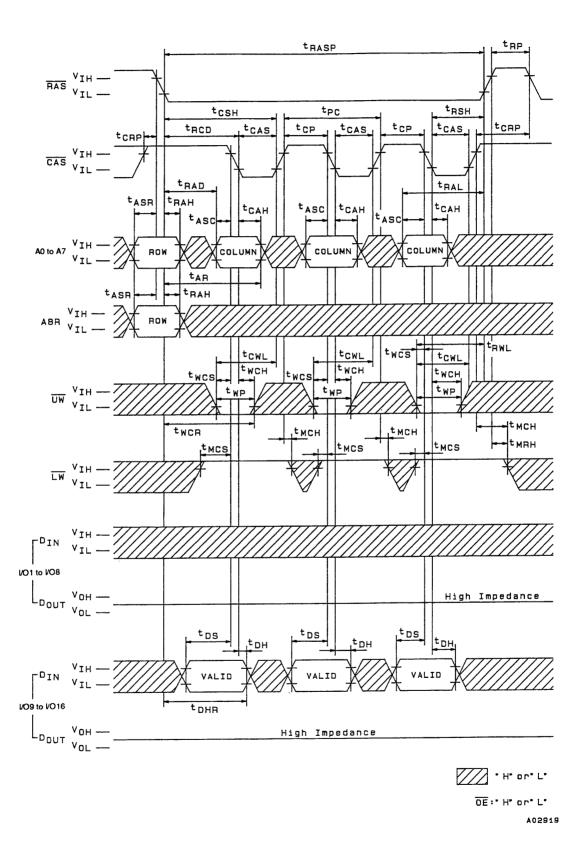


Fast Page Mode Early Write Cycle

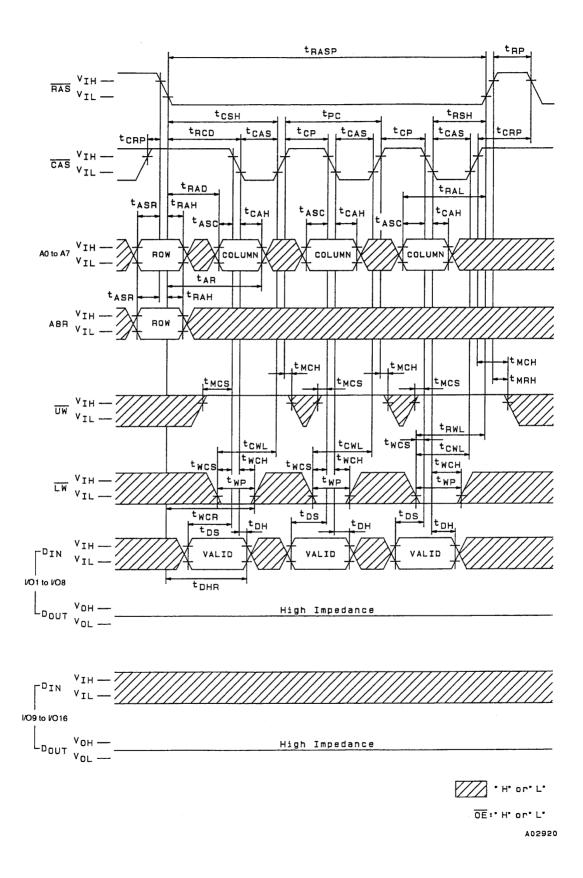


0E:. H. ou. f.

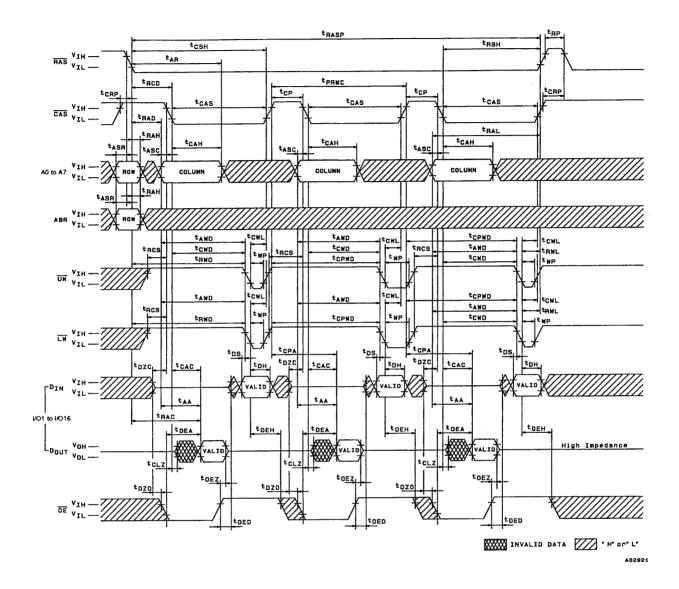
Fast Page Mode Upper Byte Early Write Cycle



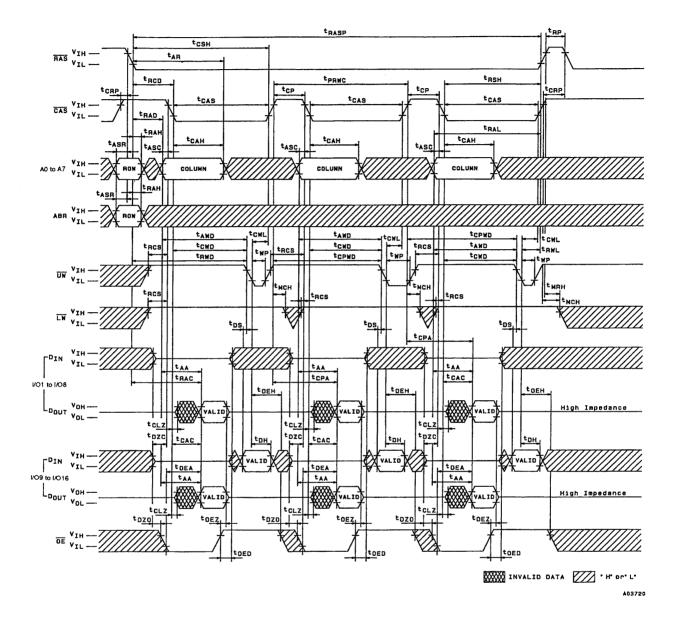
Fast Page Mode Lower Byte Early Write Cycle



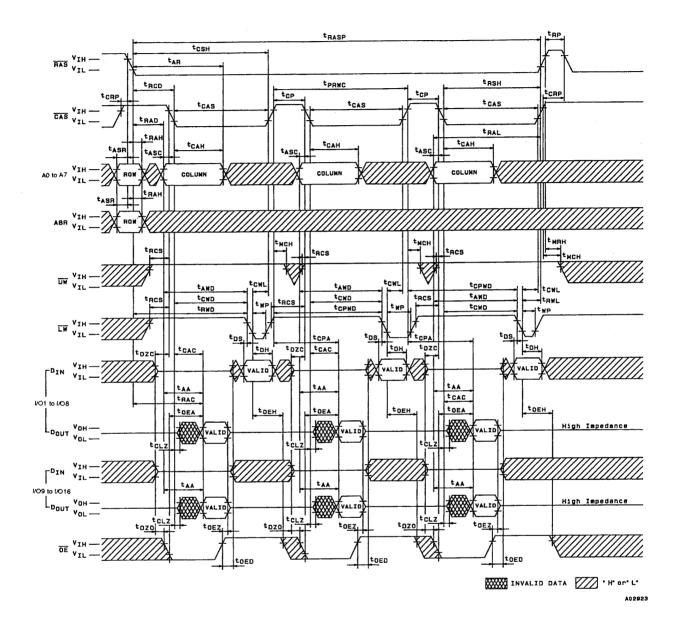
Fast Page Mode Read-Modify-Write Cycle



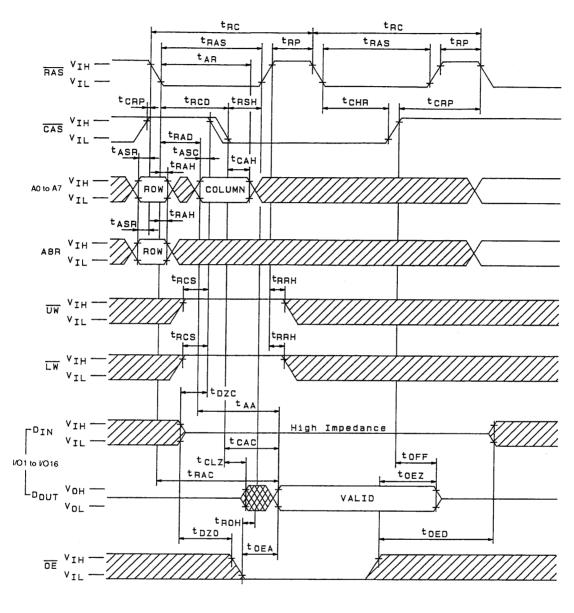
Fast Page Mode Read-Modify Upper Byte Write Cycle



Fast Page Mode Read-Modify Lower Byte Write Cycle



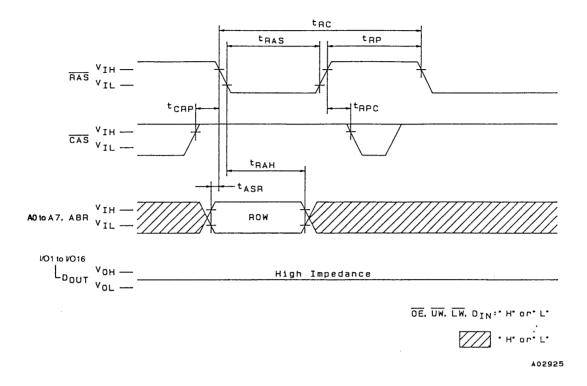
Hidden Refresh Cycle



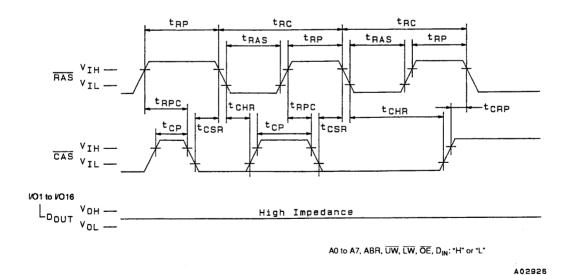
INVALID DATA .H. ob. f.

A02924

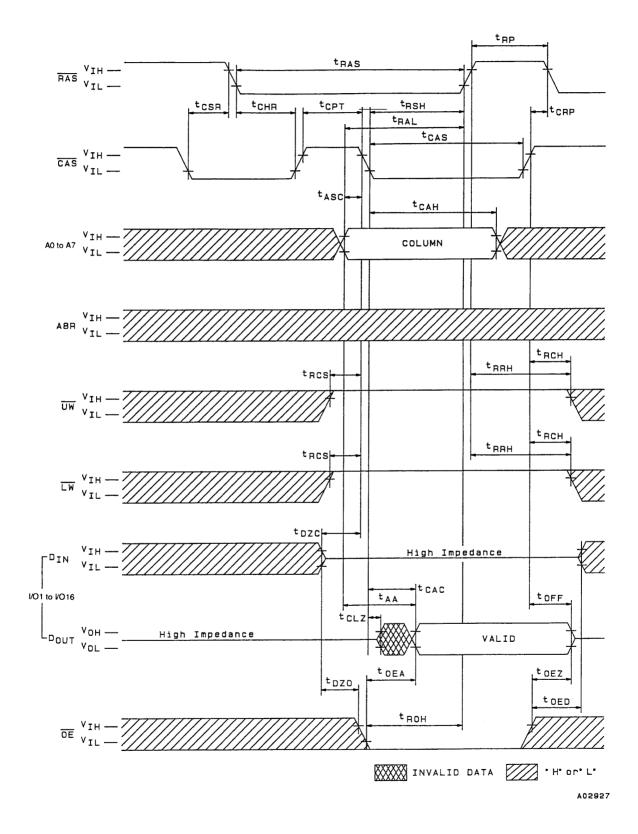
RAS-Only Refresh Cycle



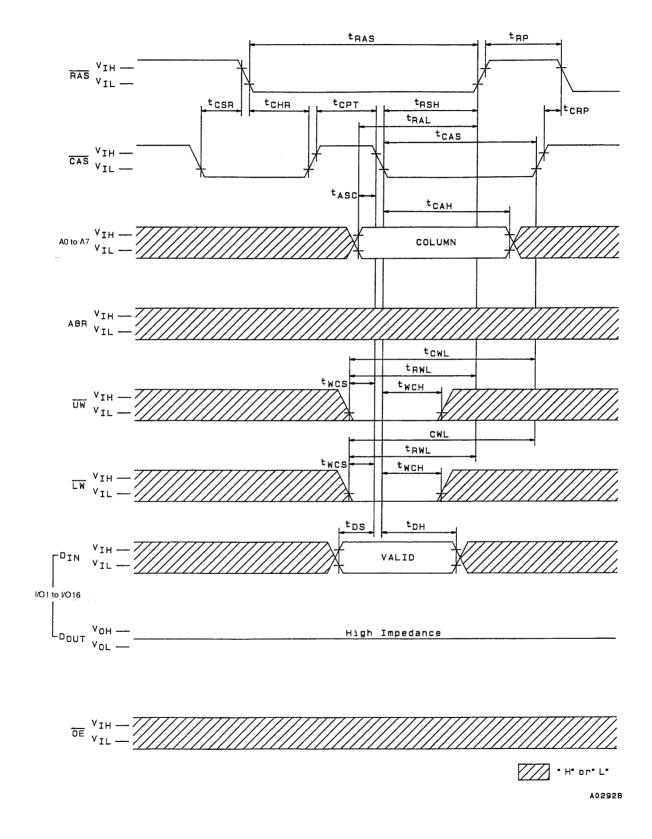
CAS-Before-RAS Refresh Cycle



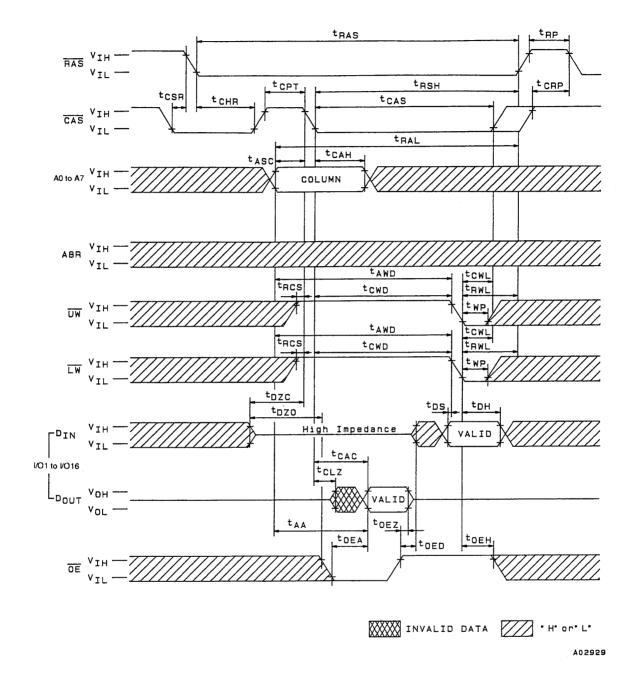
CAS-Before-RAS Refresh Counter Test Cycle (Read)



CAS-Before-RAS Refresh Counter Test Cycle (Write)



CAS-Before-RAS Refresh Counter Test Cycle (Read-Modify-Write)



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